

# Yee-wen Yen

## List of Publications by Year in descending order

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38  
papers

310  
citations

933447

10  
h-index

940533

16  
g-index

38  
all docs

38  
docs citations

38  
times ranked

153  
citing authors

#	ARTICLE	IF	CITATIONS
1	Femtosecond pulse laser fabrication of zinc oxide quantum clusters/nanoparticles and their electrical, optical, and chemical characteristics. <i>Journal of Colloid and Interface Science</i> , 2022, 614, 310-321.	9.4	3
2	The Effect of Increasing Nickel Content on the Microstructure, Hardness, and Corrosion Resistance of the CuFeTiZrNi <sub>x</sub> High-Entropy Alloys. <i>Materials</i> , 2022, 15, 3098.	2.9	5
3	Interfacial Reactions in the Sn-3.0Ag-0.5Cu/C194 Couples. , 2022, , .		1
4	Investigation of phase equilibria of the Au-Ni-Sn ternary system and interfacial reactions in the Au/Sn/Ni/Cu multilayer couple. <i>Materials Chemistry and Physics</i> , 2022, 289, 126494.	4.0	2
5	Interfacial Reactions in Lead-Free Solder/Cu-2.0Be (Alloy 25) Couples. <i>Journal of Electronic Materials</i> , 2021, 50, 903-913.	2.2	5
6	Effect of Multiple Reflowing Processes on Interfacial Reactions and Mechanical Properties between Sn-9.0Åwt.%Zn, Sn-3.0Åwt.%Ag-0.5Åwt.%Cu Solders and Ag Substrate. <i>Journal of Electronic Materials</i> , 2020, 49, 257-267.	2.2	1
7	Study of Interfacial Reactions Between Lead-Free Solders and Cu-xZn Alloys. <i>Journal of Electronic Materials</i> , 2019, 48, 170-181.	2.2	4
8	Interfacial Reactions Between Lead-Free Solders and Ni-Pd-Co Alloys. <i>Jom</i> , 2019, 71, 3031-3040.	1.9	1
9	Improving the Solder Wettability Via Atmospheric Plasma Technology. , 2019, , .		5
10	Investigation of the phase equilibria at 773 K and metallic glass regions in the Ag-Al-Zr ternary system. <i>MRS Communications</i> , 2018, 8, 113-121.	1.8	3
11	Investigation of the interfacial reactions and mechanical strength in the Sn-Ag-Cu (SAC)/Cu-Be alloy (Alloy 25) couple. , 2018, , .		4
12	Impurity-induced unusual microstructural evolution and mechanical property in Sn/Cu solder joints. <i>Journal of Materials Science: Materials in Electronics</i> , 2018, 29, 12842-12849.	2.2	4
13	Interfacial reactions between lead-free solders and Cu-40Zn alloys. , 2017, , .		0
14	Phase Equilibria of the Fe-Ni-Sn Ternary System at 270Å°C. <i>Journal of Electronic Materials</i> , 2016, 45, 6208-6213.	2.2	6
15	Phase equilibria in the Au-Bi-Sn ternary system at temperatures of 80, 125, and 150 Å°C. <i>International Journal of Materials Research</i> , 2016, 107, 615-623.	0.3	1
16	Interfacial Reactions in the Ni/Sn-xZn/Cu Sandwich Couples. <i>Journal of Electronic Materials</i> , 2016, 45, 203-211.	2.2	4
17	A Novel Electronic Packaging Method to Replace High-Temperature Sn-Pb Solders. <i>Journal of Electronic Materials</i> , 2015, 44, 3914-3919.	2.2	2
18	Interfacial Reactions in Sn/Ni-xW Couples. <i>Journal of Electronic Materials</i> , 2015, 44, 909-915.	2.2	5

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19	Interfacial Reactions of Sn, Sn-3.0Ag-0.5Cu, and Sn-9Zn Lead-Free Solders with Fe-42Ni Substrates. Journal of Electronic Materials, 2014, 43, 187-194.	2.2	17
20	Interfacial reactions between SAC405 and SACNG lead-free solders with Au/Ni(P)/Cu substrate reflowed using the CO <sub>2</sub> laser and hot-air methods. International Journal of Materials Research, 2013, 104, 637-642.	0.3	3
21	Phase equilibria of the Sn-Bi-Cu ternary system in advanced microelectronic packaging. , 2012, , .		0
22	Interfacial Reactions Between Sn-Zn Alloys and Au Substrate. Journal of Electronic Materials, 2012, 41, 3284-3291.	2.2	2
23	Interfacial Reactions in Sn/Fe-xNi Couples. Journal of Electronic Materials, 2012, 41, 144-152.	2.2	12
24	Interfacial Reactions of Sn-58Bi and Sn-9Zn Lead-Free Solders with Au/Ni/SUS304 Multilayer Substrate. Journal of Electronic Materials, 2010, 39, 2412-2417.	2.2	15
25	Abnormal spalling phenomena in the Sn-0.7Cu/Au/Ni/SUS304 interfacial reactions. Journal of Materials Research, 2010, 25, 2278-2286.	2.6	10
26	Interfacial reactions of Sn-0.7Cu, Sn-58Bi and Sn-9Zn lead-free solders with the Au/Ni/SUS 304 substrate. , 2009, , .		0
27	Interfacial Reactions Between Pb-Free Solders and In/Ni/Cu Multilayer Substrates. Journal of Electronic Materials, 2009, 38, 93-99.	2.2	9
28	Interfacial Reactions of Sn-9Zn-xCu (x=1, 4, 7, 10) Solders with Ni Substrates. Journal of Electronic Materials, 2009, 38, 2222-2227.	2.2	26
29	Cross-Interaction Between Au/Sn and Cu/Sn Interfacial Reactions. Journal of Electronic Materials, 2009, 38, 2257-2263.	2.2	15
30	Aging effects on interfacial reactions between Cu addition into the Sn-9Zn lead-free solder and Au substrate. , 2009, , .		0
31	Interfacial Reactions between Lead-Free Solders and the Multilayer Au/Ni/SUS304 Substrate. International Journal of Materials Research, 2009, 100, 672-676.	0.3	13
32	Investigation of Dissolution Behavior of Metallic Substrates and Intermetallic Compound in Molten Lead-free Solders. Journal of Electronic Materials, 2008, 37, 73-83.	2.2	41
33	Driver IC and COG Package Design. IEEE Transactions on Components and Packaging Technologies, 2008, 31, 399-406.	1.3	6
34	Effect of minor addition of Pb upon interfacial reactions and mechanical properties at Sn-3.0Ag-0.5Cu/Cu and Sn-58Bi/Cu solder joints. International Journal of Materials Research, 2008, 99, 1256-1261.	0.3	4
35	Effect of Cu addition on interfacial reactions between Sn-9Zn lead-free solder and Ni substrate. Journal of Materials Research, 2007, 22, 2663-2667.	2.6	23
36	Investigation of the Phase Equilibria of Sn-Cu-Au Ternary and Ag-Sn-Cu-Au Quaternary Systems and Interfacial Reactions in Sn-Cu/Au Couples. Journal of Electronic Materials, 2007, 36, 147-158.	2.2	24

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37	Study of interfacial reactions between Sn-Ag-Cu alloys and Au substrate. International Journal of Materials Research, 2007, 98, 496-500.	0.3	5
38	Effect of Cu addition on interfacial reaction between Sn-Zn solder and Ag. Journal of Materials Research, 2006, 21, 2986-2990.	2.6	29